

Customer No.: 31561
Application No.: 10/605,056
Docket No.: 9388-US-PA

REMARKS

Present Status of the Application

This is a full and timely response to the outstanding non-final Office Action mailed on March 31, 2005. The Office Action has rejected claims 1-2, 5, 10 and 13 under 35 U.S.C. 102(b) as being anticipated by Yamashita (US Patent No. 5,509,203) and claims 3-4 under U.S.C. 103(a) as being unpatentable over Yamashita in view of Lin et al. (US Patent No. 5,200,362).

Claims 1-13 remain pending of which claim 1 has been amended and claims 3-6 have been cancelled to more accurately describe the invention. It is believed that no new matter is added by way of these amendments made to the claims or otherwise to the application.

Applicant has most respectfully considered the remarks set forth in this Office Action. Regarding the obvious rejections, it is however strongly believed that the cited references are deficient to adequately teach the claimed features as recited in the presently pending claims. The reasons that motivate the above position of the Applicant are discussed in detail hereafter, upon which reconsideration of the claims is most earnestly solicited.

Discussion of the claim rejection under 35 USC 102

The Office Action rejected claims 1-2, 5, 10 and 13 under 35 USC 102(b) as being anticipated by Yamashita et al. (US5,509,203, Yamashita hereinafter).

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Applicants respectfully disagree and traverse the above rejections as set forth below. Independent claim 1 is allowable for at least the reason that Yamashita fails to teach or disclose each and every features of claim 1. More specifically, Yamashita at least fails to teach or disclose a step of "...forming a conductive body inside the openings, wherein a formation of the conductive body is completed when the step of forming the conductive body inside the openings is concluded..." as required by the claim 1.

Instead, Yamashita teaches that the rod formed solders 4a, in which the Office alleged to be equivalent to the conductive layer of the instant case, are pre-formed. After the rod formed solders 4a are formed with equal diameter and equal length, they are then fitted into the openings 6a (col. 5, ln. 23-25). The present invention teaches that the formation of the conductive body occurs inside the opening. In other words, the formation of conductive body is concurrent with the step of forming the conductive body inside the opening. Accordingly, Applicants respectfully submit that Yamashita cannot possibly anticipate the claimed invention in this regard, and therefore claim 1 should be allowed. Claims 2, 5, 10 and 13, which depend from Claim 1, directly or indirectly, are also patentable over Yamashita, at least because of their dependency from an allowable base claim.

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For at least the foregoing reasons, Applicants respectfully submit that claims 1-2, 5, 10 and 13 patently define over Yamashita, and therefore should be allowed. Reconsideration and withdrawal of the above rejections is respectfully requested.

Discussion of the claim rejection under 35 USC 103

The Office Action rejected claims 3-4 under 35 USC 103(a) as being unpatentable over Yamashita in view of Lin et al. (US Patent 5,200,362, hereinafter Lin).

Claims 3-4 have been cancelled to render to the rejection moot. Nevertheless, since Yamashita is silent about forming a conductive body inside the openings, wherein a formation of the conductive body is completed when the step of forming the conductive body inside the openings is concluded, still Lin cannot cure the specific deficiencies of Yasmahita.

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CONCLUSION

For at least the foregoing reasons, it is believed that all the pending claims 1-2, 7-13 of the present application patently define over the prior art and are in proper condition for allowance. If the Examiner believes that a telephone conference would expedite the examination of the above-identified patent application, the Examiner is invited to call the undersigned.

Respectfully submitted

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